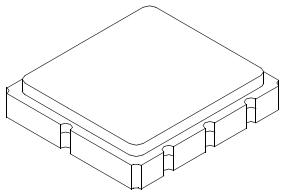
RFMi
A BRAND OF AKOUSTIS

RoHS compliant

SF2437D

480 MHz SAW Filter

- ***High Performance SAW Filter***
- ***3.8 x 3.8 mm Surface-mount Package***
- ***Complies with Directive 2002/95/EC (RoHS)***
- ***Moisture Sensitivity Level: 1***



SM3838-8

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any Two Active Terminals	3	VDC
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range	-40 to +95	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 10 sec	

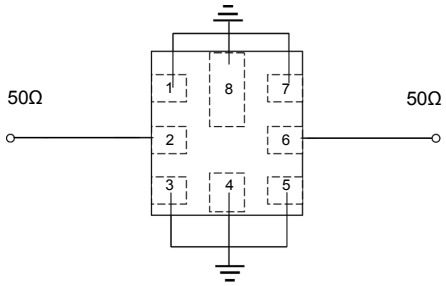
Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			480		MHz
Insertion Loss (470 to 482 MHz)	ILmin			2.4	3.5	dB
(482 to 490 MHz)				1.8	3.0	
Amplitude Ripple (470 to 490 MHz)				1.9	2.5	dB
Attenuation (Reference level from 0dB)						dB
0 to 350 MHz			40	45		
350 to 450 MHz			23	28		
500 to 518 MHz			34	40		
540 to 560 MHz			36	43		
560 to 600 MHz			36	39		
Temperature Coefficient of Frequency				-36		ppm/k

Case Style	3.8 x 3.8 mm Nominal Footprint
Lid Symbolization, Y=year, WW=week, S=shift, Dot=pin 1 indicator	B47, YWWS

Electrical Connections

Connection	Terminals
Input	2
Output	6
Case Ground	All others

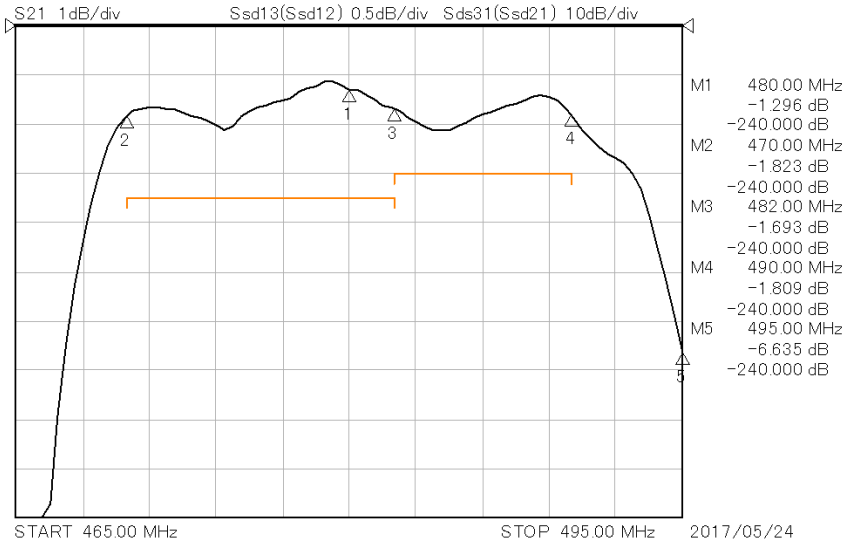


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

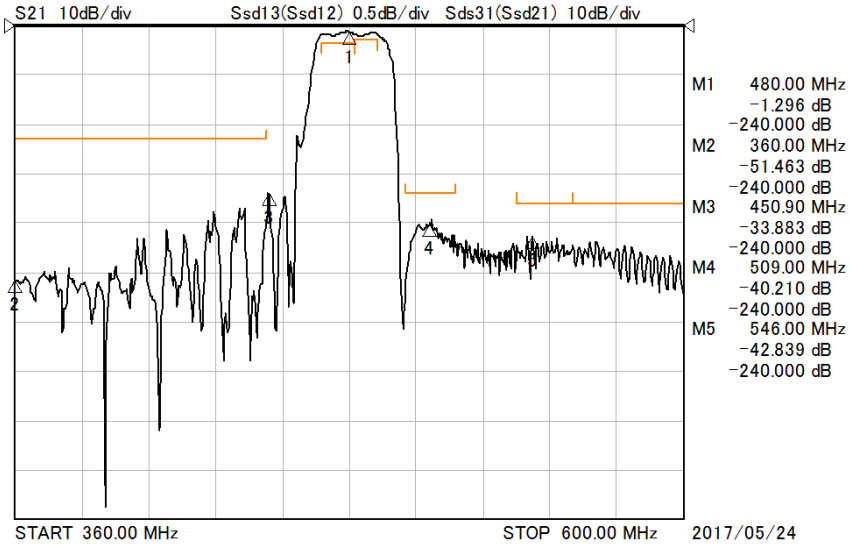
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

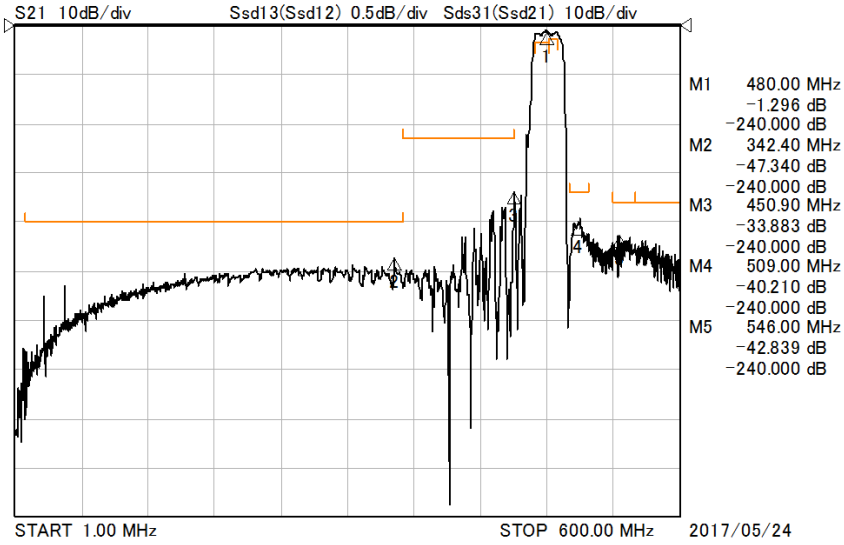
Frequency Characteristics



Format: LogMag REF: 0dB

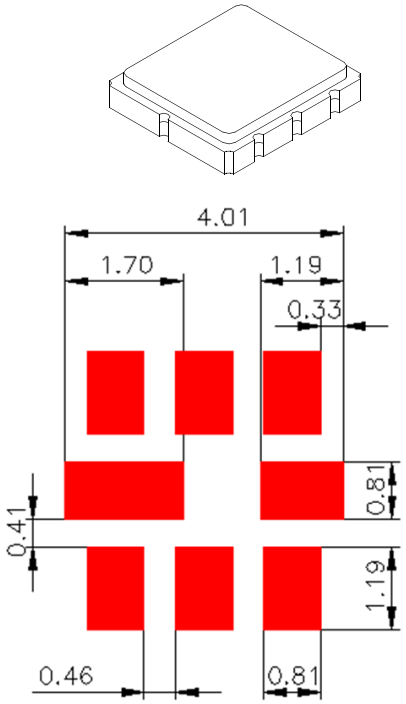


Format: LogMag REF: 0dB



SM3838-8 Case

8-Terminal Ceramic Surface-Mount Case
3.8 X 3.8mm Nominal Footprint



PCB Footprint

Case Dimensions

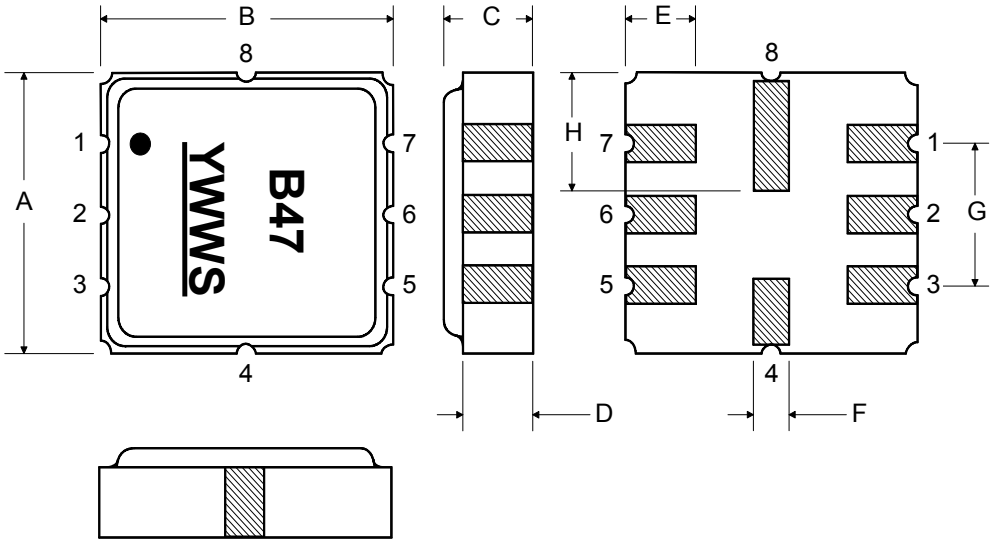
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.65	3.8	3.95	0.14	0.15	0.155
B	3.65	3.8	3.95	0.14	0.15	0.155
C	-	-	1.40	-	-	0.055
D	-	1.10	-	-	0.043	-
E	-	1.0	-	-	0.04	-
F	-	0.6	-	-	0.024	-
G	-	2.54	-	-	0.100	-
H	-	1.50	-	-	0.059	-

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic

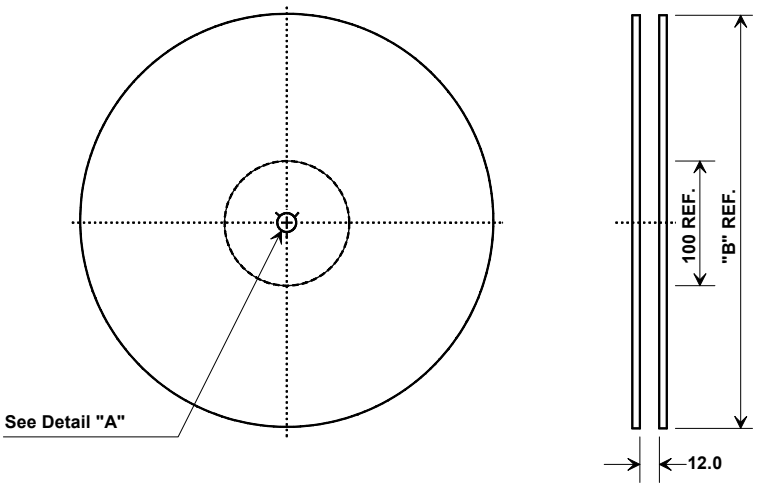
TOP VIEW

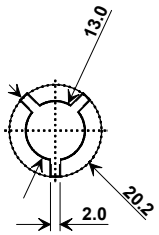
BOTTOM VIEW



Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

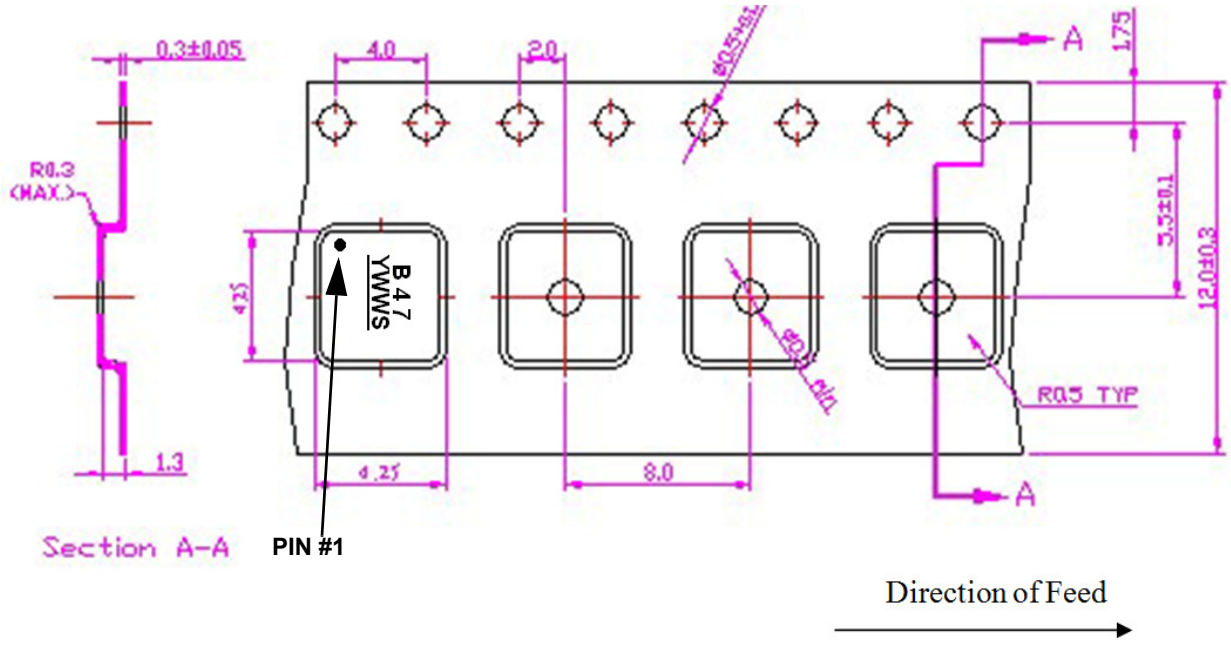




"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.3 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180ºC for 60~90 seconds.
2. Ascending time to preheating temperature 150ºC shall be 30 seconds min.
3. Heating shall be fixed at 220ºC for 50~80 seconds and at 260ºC +0/-5ºC peak (10 seconds).
4. Time: 5 times maximum.